



Material Content Data Sheet



Sales Product Name		SAK-XE167FH-200F100L AB		Issued		27. September 2017		
MA#		MA001049118						
Package		PG-LQFP-144-13		Weight*		1421.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	71.686	5.04	5.04	50431	50431
leadframe	inorganic material	phosphorus	7723-14-0	0.105	0.01		74	
	non noble metal	zinc	7440-66-6	0.420	0.03		296	
	non noble metal	iron	7439-89-6	8.410	0.59		5916	
wire	non noble metal	copper	7440-50-8	341.472	24.02	24.65	240222	246508
	noble metal	gold	7440-57-5	4.202	0.30	0.30	2956	2956
	encapsulation	organic material	carbon black	1333-86-4	4.845	0.34		3408
encapsulation	plastics	epoxy resin	-	130.815	9.20		92027	
	inorganic material	silicondioxide	60676-86-0	833.340	58.63	68.17	586246	681681
leadfinish	non noble metal	tin	7440-31-5	9.120	0.64	0.64	6416	6416
plating	noble metal	silver	7440-22-4	2.668	0.19	0.19	1877	1877
glue	plastics	epoxy resin	-	3.600	0.25		2533	
	noble metal	silver	7440-22-4	10.800	0.76	1.01	7598	10131
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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